

The Electronics Division Hoffman Scholarship Application Form

2018 Essay Topic:
“Tailoring Material Properties through Defect Engineering for Electronic Ceramics”

Application Deadline: May 15th annually

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| Full Name |
| Email Address |   |
| Mailing Address |
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|  |
| Name of Undergraduate Department |
| University |
| Total GPA Science GPA Total Credits |
| PSAT/SAT/ACT Scores | Date of Exam |
| Extracurricular Activities |
| (attach additional sheets if necessary) |
|  |
| Faculty Advisor\* |
| Address |
|  |  |
|  |  |
| Telephone | ( ) E-mail |
| Applicant's Signature | Date |
| Advisor's Signature | Date |
| \* Essay and Recommendation letter must be emailed directly to: |
| Hui (Claire) Xiong Boise State University  clairexiong@boisestate.edu  Phone: 208.426.5671  Nominations should also be sent to Erica Zimmerman at ezimmerman@ceramics.org. |